

08-23-2000

FORM PTO-1595

RECORDATION

DEPARTMENT OF COMMERCE

(Rev. 6-93)

PA1



Patent and Trademark Office

OMB No. 0651-0011 (exp. 4/94)

101440705

Tab settings →→→

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

1. Jürgen Högerl

2. Name and address of receiving party(ies):

Name: Siemens AktiengesellschaftInternal Address: ZT GG VM(Additional name(s) of conveying party(ies) attached) Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____Street Address: Postfach 22 16 34City: München State: Germany ZIP: 80506Execution Date: 05/30/00 for 1Additional name(s) & address(es) attached ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/577,065

B. Patent No.(s)

Additional numbers attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lerner and Greenberg, P.A.

Internal Address: _____

Street Address: P.O. Box 2480City: Hollywood State: FL ZIP: 33022

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)\$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page by deposit account)

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*WERNER H. STIMER
REG. NO. 34,956

Name of Person Signing

Signature

07/25/00

Date

Total number of pages including cover sheet, attachments, and document:

2

Docket No.: GR 99 P 1885

ASSIGNMENT

WHEREAS I, JÜRGEN HÖGERL, residing at REGENSBURG, Germany, have invented certain new and useful improvements in a

SEMICONDUCTOR MODULE HAVING INTERCONNECTED SEMICONDUCTOR
CHIPS DISPOSED ONE ABOVE THE OTHER

for which an application for Letters Patent of the United States of America was executed on the date of execution of this assignment;

WHEREAS, SIEMENS AKTIENGESELLSCHAFT, a German corporation doing business at München, Germany is desirous of acquiring the entire interest in the invention, and in any and all Letters Patent of the United States that may be obtained therefor;

NOW, THEREFORE, be it known that for and in consideration of my employment by the said corporation and other valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, I have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said corporation, its legal representative, successors and assigns, the full and exclusive right to the said invention as fully set forth and described in the above-mentioned application, and to the application and any and all divisions and continuations thereof, and any and all Letters Patent of the United States which may be granted therefore, and any and all reissues of the Letters Patent, the same to be held and enjoyed by the said corporation, its legal representatives, successors and assigns, to the full end of the term for which the Letters Patent may be granted or may be reissued or extended, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

AND I hereby authorize the Commissioner of Patents to issue any and all Letters Patent of the United States on the invention or resulting from the application and from any and all divisions and continuations thereof of the said corporation as the assignee of the entire right, title and interest in and to the same.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal this
day of May 18, 2000.

In the presence of:

W. J. Hoff

Jürgen Högerl (L.S.)
JÜRGEN HÖGERL